NOTES:
1. FOR PCB LAYOUT SEE VICOR APPLICATION DRAWING 39983.
2. THE SOLDERING METHOD USED FOR CHIPS (AND OPTIONAL HEATSINK GROUNDING) IS IMPORTANT WHEN SELECTING A THERMAL INTERFACE MATERIAL (TIM). THE PHASE-CHANGE TIM SHOWN IN THESE ILLUSTRATIONS MAY BE DAMAGED BY TEMPERATURES OVER 125°C, SO TWO ASSEMBLY PROCEDURES ARE DESCRIBED BELOW:
   A) FOR HAND-SOLDERING ONLY,
   B) FOR WAVE-SOLDERING AND/OR HAND-SOLDERING.
3. CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRING DURING INSTALLATION AS THIS WOULD EXPOSE THE CHIP TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 3.1 LBF (13.8 N) PER PUSH-PIN.
4. RoHS COMPLIANT PER CST-0001 LATEST REVISION.

PUSH-PIN SELECTION

HEATSINK SELECTION

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